REVISION B

DESIGNED & DIMENSIONED
IN MILLIMETERS[INCHES]

HDBNC-J-P-XX-ST-EM1

GENDER
-J: JACK

TYPE
-P: PCB

PLATING SPECIFICATION
-HF: 30µ" GOLD CENTER CONTACT,
3µ" GOLD OUTER CONTACT
-HN: 30µ" GOLD CENTER CONTACT,
100µ" NICKEL OUTER CONTACT
-GF: 10µ" GOLD CENTER CONTACT,
3µ" GOLD OUTER CONTACT
-GN: 10µ" GOLD CENTER CONTACT,
100µ" NICKEL OUTER CONTACT
(SEE TABLE 1)

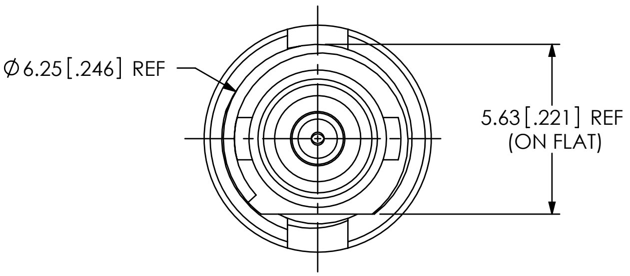
ORIENTATION
-ST: STRAIGHT

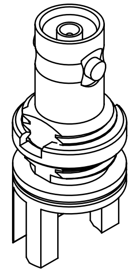
TERMINATION
-EM1: EDGE MOUNT .062 BOARD

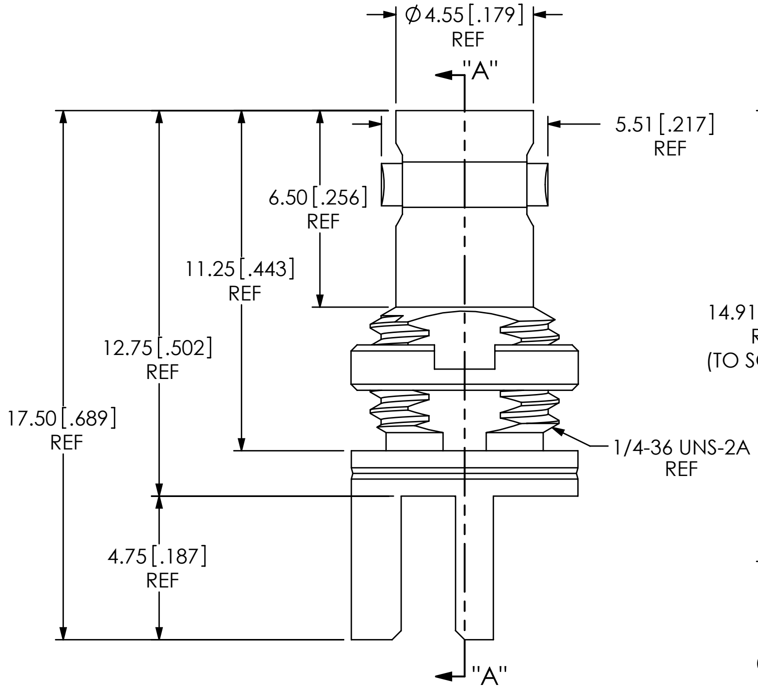
TABLE 1

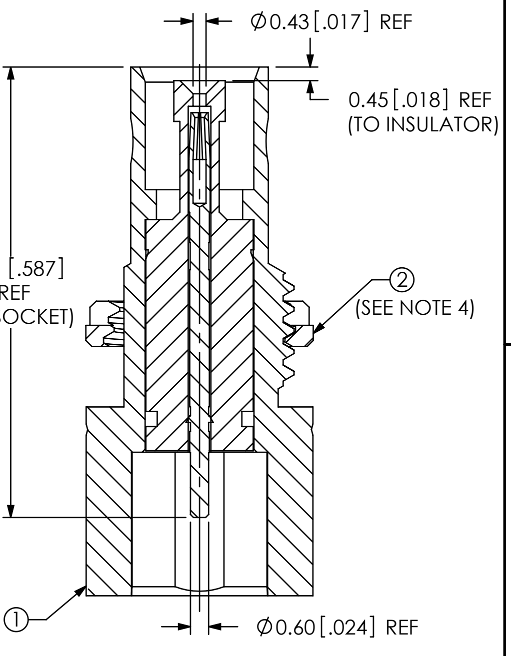
ITEM	COMPONENT	-HF	-HN	-GF	-GN
1	SUB ASSEMBLY	SUB-HDBNC-J-P-HF-ST-EM1	SUB-HDBNC-J-P-HN-ST-EM1	SUB-HDBNC-J-P-GF-ST-EM1	SUB-HDBNC-J-P-GN-ST-EM1
2	NUT	HDBNC-NUT-001-N			

DO NOT
SCALE FROM
THIS PRINT

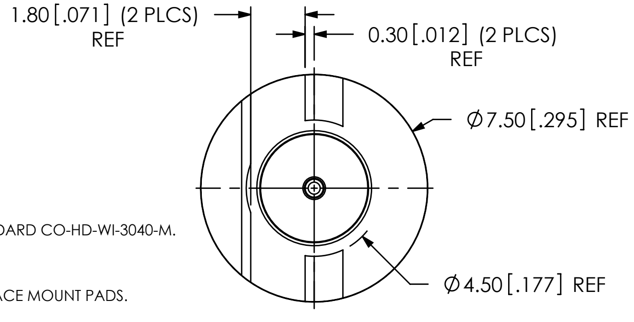






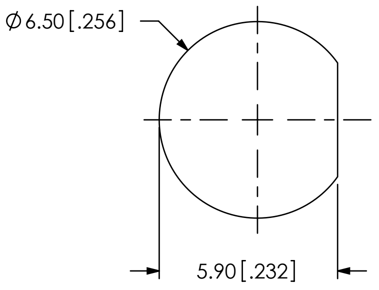


SECTION "A"-"A"



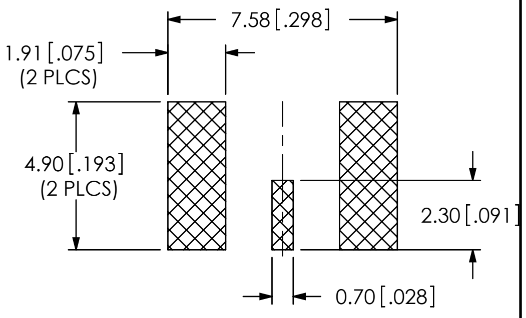
RECOMMENDED MOUNTING HOLE

2.70 [.079] MAX PANEL THICKNESS



RECOMMENDED PCB LAYOUT

(SEE NOTE 5 & 6)



NOTES:

1. ⟨C⟩ REPRESENTS A CRITICAL DIMENSION.
2. NOTE DELETED.
3. PRODUCT TO BE PACKAGED PER PACKING STANDARD CO-HD-WI-3040-M.
   TRAY: TY-SMA-001-1
   COVER: TY-SMA-001-2
4. NUT TO BE PACKAGED SEPARATELY.
5. STENCIL APERTURES TO BE 1:1 WITH THE PCB SURFACE MOUNT PADS.
   STENCIL THICKNESS TO BE 0.13 [.005].
6. A FIXTURE IS RECOMMENDED DURING THE REFLOW PROCESS TO HOLD THE CONNECTOR STRAIGHT AND PARALLEL WITH THE PCB.
   CONTACT IPG FOR MORE DETAILS.

F:\DWG\MISC\MKTG\HDBNC-J-P-XX-ST-EM1 -MKT.SLDDRW

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN MILLIMETERS.
TOLERANCES ARE:

DECIMALS	ANGLES
X.X: ±0.3 [.01]	5°
X.XX: ±0.13 [.005]	
X.XXX: ±0.051 [.0020]	

PROPRIETARY NOTE

MATERIAL:
DO NOT SCALE DRAWING
SHEET SCALE: 4:1

SOCKET: BeCu
SHELL, NUT: BRASS
INSULATOR: PTFE

samtec
520 PARK EAST BLVD, NEW ALBANY, IN 47150
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DESCRIPTION:
HD BNC 75 OHM, ST JACK EDGE MOUNT

DWG. NO.
HDBNC-J-P-XX-ST-EM1

BY: ALVIN W 02/11/2011 SHEET 1 OF 1